

# UTAC Launches wCSP, A Chip Scale Package Solution For High Speed Memory

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Provide superb flexibility for module makers in getting higher module capacity with smaller footprint

Singapore, September 3, 2001 - United Test and Assembly Center Limited ("UTAC") today announced wCSP (window Chip Scale Package), a high-performance, cost-effective and adaptive chip scale BGA package developed for high-speed memory applications. The package has low profile and fine ball pitch with enhanced electrical and thermal performance. The state-of-art package design accommodates die shrink without affecting overall package outline.

One of the key innovations of the wCSP involves the narrow strip of cavity at the center of the BT substrate. The die is attached across this cavity strip and wirebonding is done through the cavity. The cavity strip is encapsulated using conventional mold compound to enhance package robustness.

The resultant small package footprint, coupled with enhanced electrical and thermal performance, makes wCSP an excellent solution for high capacity memory modules to use in handheld PC, notebook and wireless peripherals.

"This revolutionary package will cater for memory device speed as high as 400Mhz. We are further developing prototype package to handle device speeds of more than 400MHz using flip chip technology interconnections," said Lee Hoong Leong, vice president of research and development at UTAC. "In addition, the unique wCSP design ensure high yield and consistent manufacturability. This enables us to drive down the overall cost of production."

UTAC offers two versions of wCSP solution. The Standard version has a maximum package thickness of 1.2 mm. The Ultra Low Profile version can be achieved with maximum thickness of 1.0 mm through a thinner mold cap which allow for exposed silicon back. Both the Standard and Ultra Low Profile versions are available in body sizes from 8 x 8 mm to 11 x 18 mm.

About United Test and Assembly Center Ltd (UTAC)

United Test and Assembly Center Ltd. (UTAC), founded on 16th March 1998, is a QS9000/ISO9001/SAC certified semiconductor assembly and test services provider. We offer full turnkey services from wafer sort / laser repair, packaging, Test / Burn in, Mark-Scan-Pack and drop shipment services. In addition, we provide customers with value-added services in package design and simulation, test program development and device characterization, failure analysis services and full reliability test services.

UTAC is committed to provide customers one-stop turnkey semiconductor assembly and testing services for wide spectrum of memory, logic and mixed signal devices.

UTAC World Wide Web address is [www.utac.com.sg](http://www.utac.com.sg).